

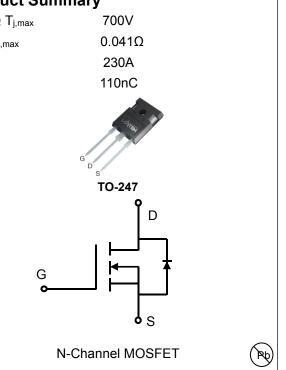
# Lonten N-channel 650V, 78A, 0.041Ω LonFET<sup>™</sup> Power MOSFET

#### Description **Product Summary** LonFET<sup>™</sup> Power MOSFET is fabricated using V<sub>DS</sub> @ T<sub>j,max</sub> 700V advanced super junction technology. The resulting 0.041Ω R<sub>DS(on),max</sub> 230A device has extremely low on resistance, making it IDM especially suitable for applications which require 110nC Q<sub>g,typ</sub> superior power density and outstanding efficiency. **Features** Ultra low R<sub>DS(on)</sub> ٠ Ultra low gate charge (typ. $Q_g = 110nC$ ) TO-247 ٠ 100% UIS tested ٠

**RoHS** compliant ٠

#### **Applications**

- Power faction correction (PFC). ٠
- Switched mode power supplies (SMPS). ٠
- Uninterruptible power supply (UPS). ٠



#### **Absolute Maximum Ratings**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	650	V
Continuous drain current ( $T_c = 25^{\circ}C$ )	ID	78	А
( T <sub>c</sub> = 100°C )		46	А
Pulsed drain current <sup>1)</sup>	I <sub>DM</sub>	230	А
Gate-Source voltage	V <sub>GSS</sub>	±30	V
Avalanche energy, single pulse 2)	E <sub>AS</sub>	2350	mJ
Power Dissipation TO-247 ( $T_c = 25^{\circ}C$ )	5	500	W
- Derate above 25°C	PD	4.0	W/°C
Operating and Storage Temperature Range	Tj, Tstg	-55 to +150	°C
Continuous diode forward current	Is	78	А
Diode pulse current	I <sub>S,pulse</sub>	230	А

#### **Thermal Characteristics TO-247**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	0.25	°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>0JA</sub>	62	°C/W
Soldering temperature, wavesoldering only allowed	T <sub>sold</sub>	260	°C
at leads. (1.6mm from case for 10s)	. 5014		<b></b>



## Package Marking and Ordering Information

Device	Device Package	Marking	Units/Tube	Units/Reel
LSB65R041GF	TO-247	LSB65R041GF	30	

## Electrical Characteristics T<sub>c</sub> = 25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0 V, I <sub>D</sub> =0.25 mA	650	-	-	V
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =0.25 mA	2.5	3.5	5.0	V
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> =650 V, V <sub>GS</sub> =0 V,				μA
		T <sub>j</sub> = 25°C	-	-	5	
		T <sub>j</sub> = 125°C	-	10	-	
Gate leakage current, Forward	IGSSF	V <sub>GS</sub> =30 V, V <sub>DS</sub> =0 V	-	-	100	nA
Gate leakage current, Reverse	I <sub>GSSR</sub>	V <sub>GS</sub> =-30 V, V <sub>DS</sub> =0 V	-	-	-100	nA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10 V, I <sub>D</sub> =39 A	-			
		T <sub>j</sub> = 25°C	-	0.036	0.041	Ω
		T <sub>j</sub> = 150°C	-	0.094	-	
Dynamic characteristics			·			
Input capacitance	Ciss	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V,	-	7710	-	
Output capacitance	Coss	f = 250 kHz	-	252	-	pF
Reverse transfer capacitance	C <sub>rss</sub>		-	6.66	-	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = 400 V, I <sub>D</sub> = 39 A	-	46	-	
Rise time	tr	R <sub>G</sub> = 10 Ω, V <sub>GS</sub> =10 V	-	52	-	ns
Turn-off delay time	t <sub>d(off)</sub>		-	342	-	
Fall time	t <sub>f</sub>	-	-	8.6	-	
Gate charge characteristics	L	1	<b>I</b>		1	1
Gate to source charge	Q <sub>gs</sub>	V <sub>DD</sub> =400 V, I <sub>D</sub> =39 A,	-	25.7	-	
Gate to drain charge	Q <sub>gd</sub>	V <sub>GS</sub> =0 to 10 V	-	42.2	-	nC
Gate charge total	Qg		-	110	-	
Gate plateau voltage	V <sub>plateau</sub>	1	-	6.0	-	V
Reverse diode characteristics		•				
Diode forward voltage	V <sub>SD</sub>	V <sub>GS</sub> =0 V, I <sub>F</sub> =39 A	-	-	1.2	V
Reverse recovery time	trr	V <sub>R</sub> =50 V, I <sub>F</sub> =39 A,	-	200	-	ns
Reverse recovery charge	Qrr	dl <sub>F</sub> /dt=100 A/µs	-	1.9	-	μC
Peak reverse recovery current	Irrm		-	18.3	-	Α

Notes:

1. Limited by maximum junction temperature, maximum duty cycle is 0.75.

2.  $I_{AS}$  = 10A,  $V_{DD}$  =60V, Starting T<sub>j</sub>= 25°C.



## **Electrical Characteristics Diagrams**

Figure 1. On-Region Characteristics

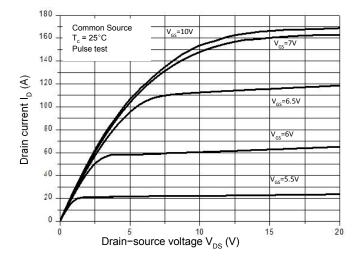


Figure 3. On-Resistance Variation vs. Drain Current

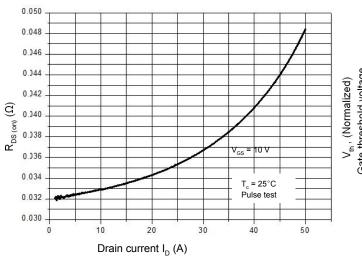


Figure 5. Breakdown Voltage vs. Temperature

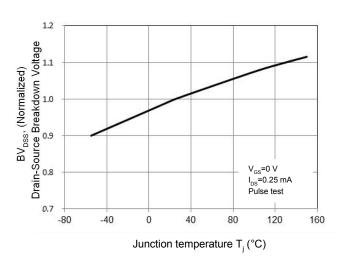


Figure 2. Transfer Characteristics

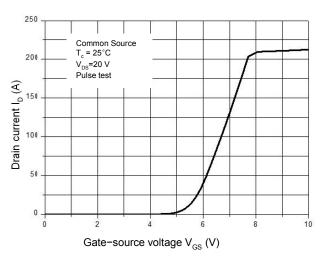


Figure 4. Threshold Voltage vs. Temperature

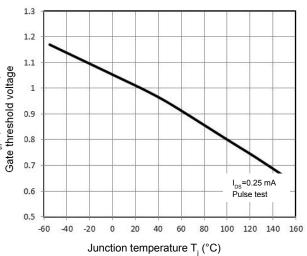
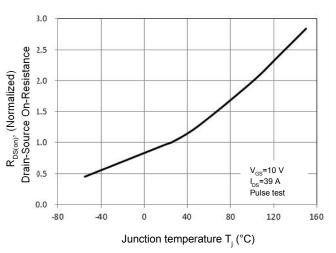
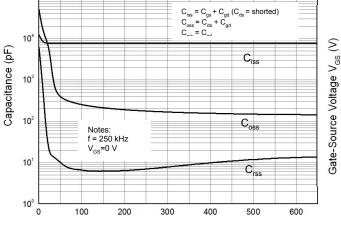


Figure 6. On-Resistance vs. Temperature





#### Figure 7. Capacitance Characteristics



Drain-Source Voltage  $V_{DS}$  (V)



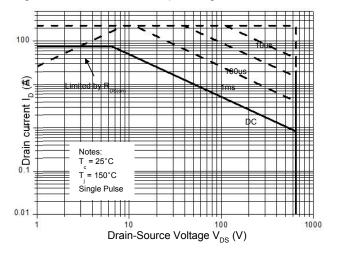
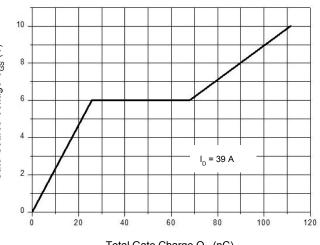
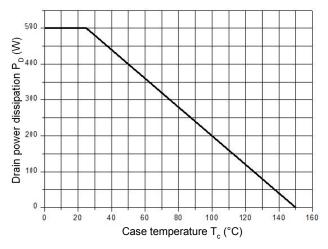


Figure 8. Gate Charge Characterist



Total Gate Charge  $Q_G$  (nC)

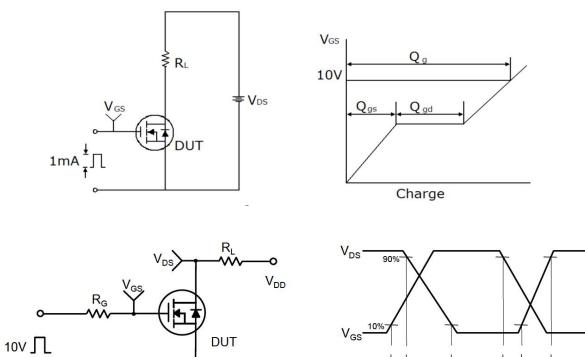






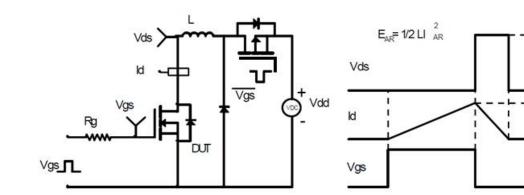
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## Gate Charge Test Circuit & Waveform



**Unclamped Inductive Switching Test Circuit & Waveforms** 

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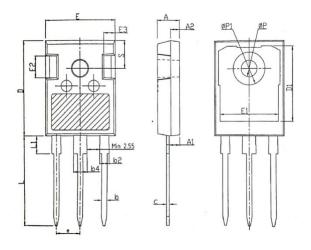


**BV**<sub>DSS</sub>

LAR

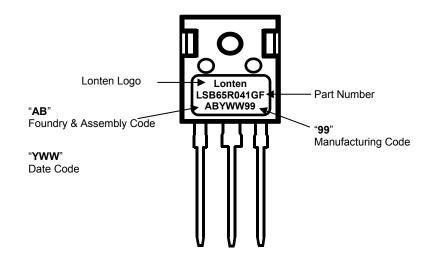


### Mechanical Dimensions for TO-247



SYMBOL		mm	
STIVIBOL	MIN	NOM	МАХ
А	4.80	5.00	5.20
A1	2.21	2.41	2.59
A2	1.85	2.00	2.15
b	1.11	1.21	1.36
b2	1.91	2.01	2.21
b4	2.91	3.01	3.21
с	0.51	0.61	0.75
D	20.80	21.00	21.30
D1	16.25	16.55	16.85
E	15.50	15.80	16.10
E1	13.00	13.30	13.60
E2	4.80	5.00	5.20
E3	2.30 2.50		2.70
е	5.44BSC		
L	19.82	19.92	20.22
L1	_	_	4.30
ØP	3.40	3.60	3.80
ØP1	_	_	7.30
S		6.15BSC	

#### **TO-247 Part Marking Information**





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